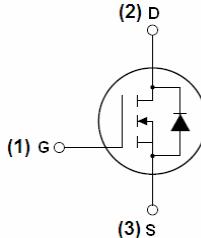


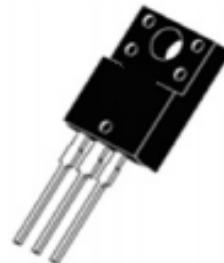
QIAOXIN N-Channel Super Trench Power MOSFET

Description

The VCRRP85T35T uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.



Schematic diagram



TO-247 top view

General Features

- $V_{DS} = 85V, I_D = 350A$
- $R_{DS(ON)} < 1.85m\Omega @ V_{GS}=10V$
- Excellent gate charge $\times R_{DS(on)}$ product
- Very low on-resistance $R_{DS(on)}$
- 175 °C operating temperature
- Pb-free lead plating
- 100% UIS tested

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

Package Marking and Ordering Information

Device Marking	Device	Device Package
VCRRP85T35T	VCRRP85T35T	TO-247

Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	85	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	350	A
Drain Current-Continuous($T_c=100^\circ C$)	$I_D (100^\circ C)$	280	A
Pulsed Drain Current	I_{DM}	1400	A
Maximum Power Dissipation	P_D	520	W
Derating factor		3.47	W/°C
Single pulse avalanche energy ^(Note 5)	E_{AS}	3800	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	R_{eJC}	0.29	°C/W
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Electrical Characteristics ($T_c=25^\circ\text{C}$ unless otherwise noted)

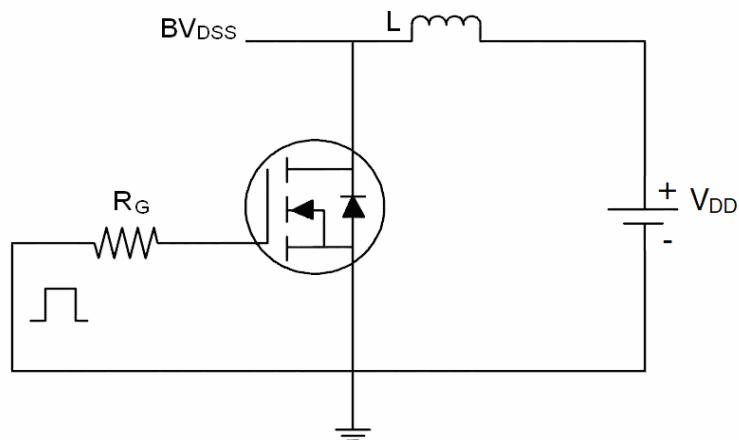
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	85	90	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=85\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	3	3.8	5	V
Drain-Source On-State Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=175\text{A}$	-	1.4	1.85	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=175\text{A}$	-	150	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C_{iss}	$V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	19500	-	PF
Output Capacitance	C_{oss}		-	2990	-	PF
Reverse Transfer Capacitance	C_{rss}		-	200	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=40\text{V}, I_{\text{D}}=100\text{A}$ $V_{\text{GS}}=10\text{V}, R_{\text{G}}=1.8\Omega$	-	35	-	nS
Turn-on Rise Time	t_r		-	98	-	nS
Turn-Off Delay Time	$t_{\text{d(off)}}$		-	110	-	nS
Turn-Off Fall Time	t_f		-	45	-	nS
Total Gate Charge	Q_g	$V_{\text{DS}}=40\text{V}, I_{\text{D}}=100\text{A}, V_{\text{GS}}=10\text{V}$	-	324	-	nC
Gate-Source Charge	Q_{gs}		-	123	-	nC
Gate-Drain Charge	Q_{gd}		-	88	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	$V_{\text{GS}}=0\text{V}, I_F= 175\text{A}$	-		1.2	V
Diode Forward Current (Note 2)	I_s		-	-	350	A
Reverse Recovery Time	t_{rr}	$T_J = 25^\circ\text{C}, I_F = I_s$ $dI/dt = 100\text{A}/\mu\text{s}$ (Note3)	-	155	-	nS
Reverse Recovery Charge	Q_{rr}		-	436	-	nC

Notes:

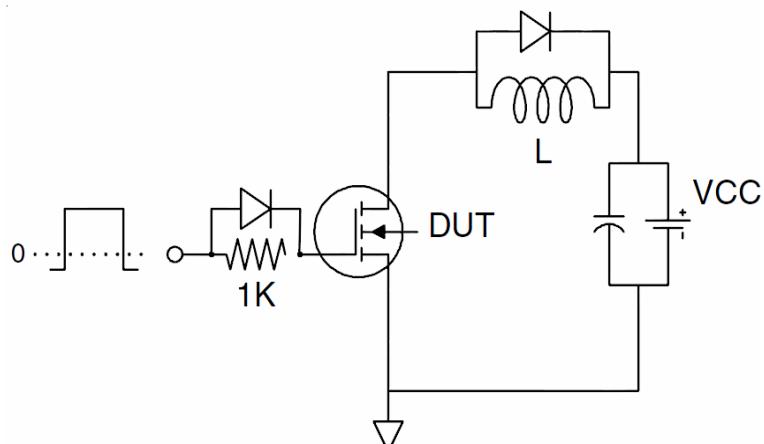
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition : $T_J=25^\circ\text{C}, V_{\text{DD}}=42.5\text{V}, V_{\text{G}}=10\text{V}, L=1\text{mH}, R_g=25\Omega$

Test Circuit

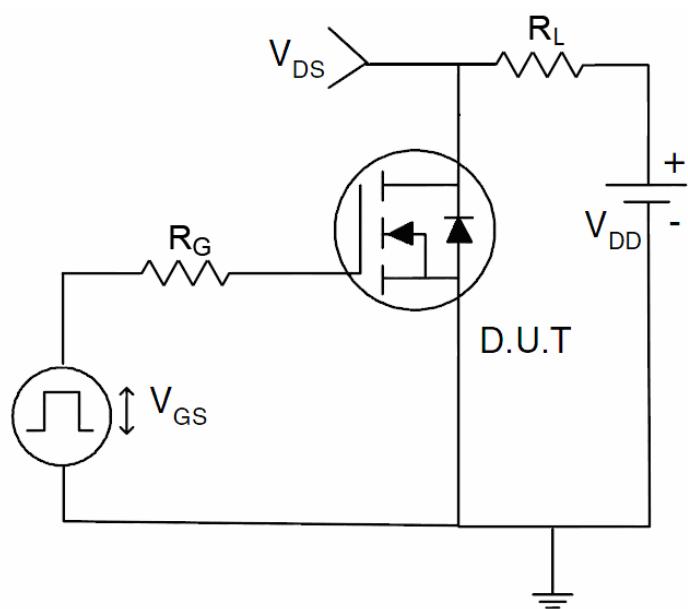
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit



Typical Electrical and Thermal Characteristics

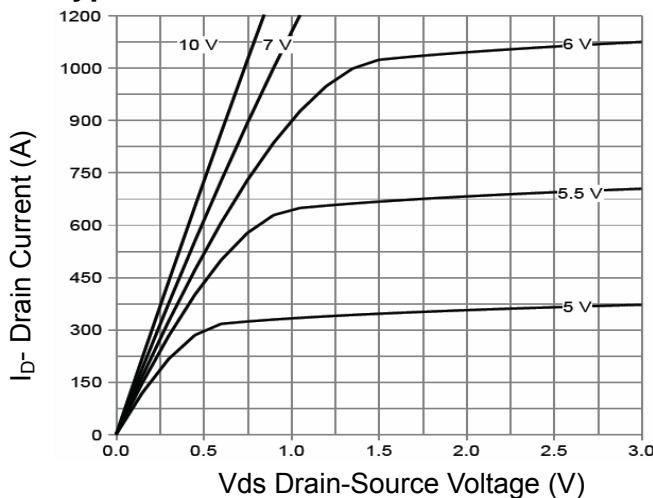


Figure 1 Output Characteristics

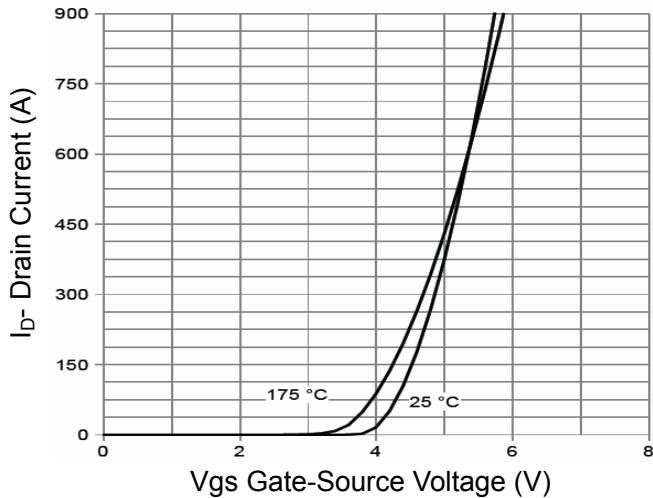


Figure 2 Transfer Characteristics

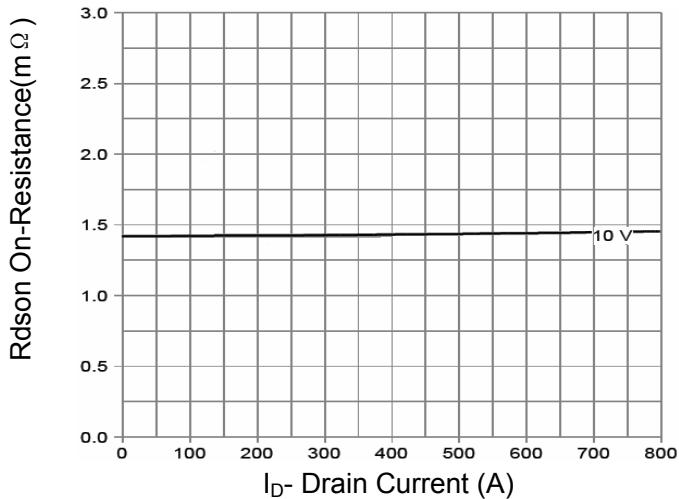


Figure 3 Rdson- Drain Current

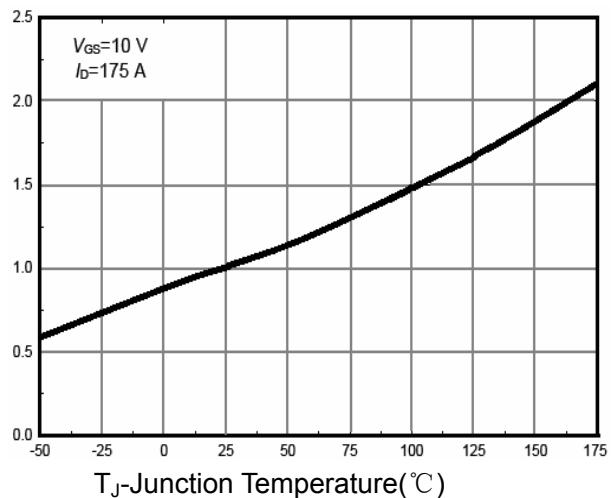


Figure 4 Rdson-JunctionTemperature

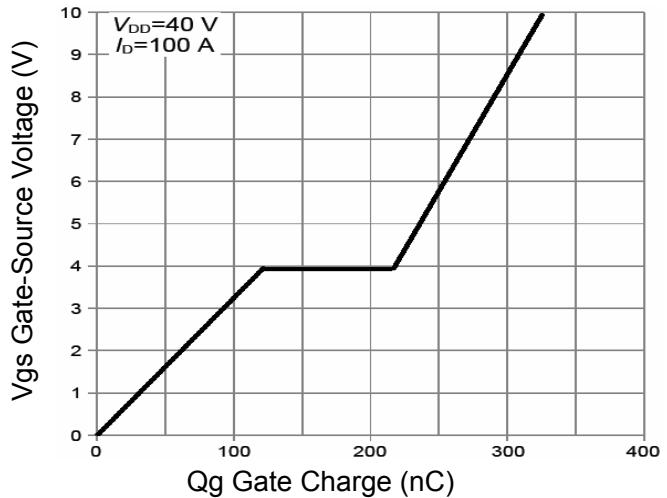


Figure 5 Gate Charge

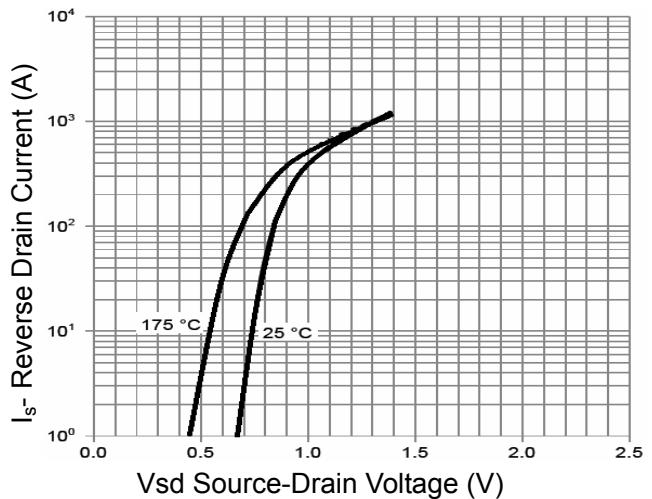


Figure 6 Source- Drain Diode Forward

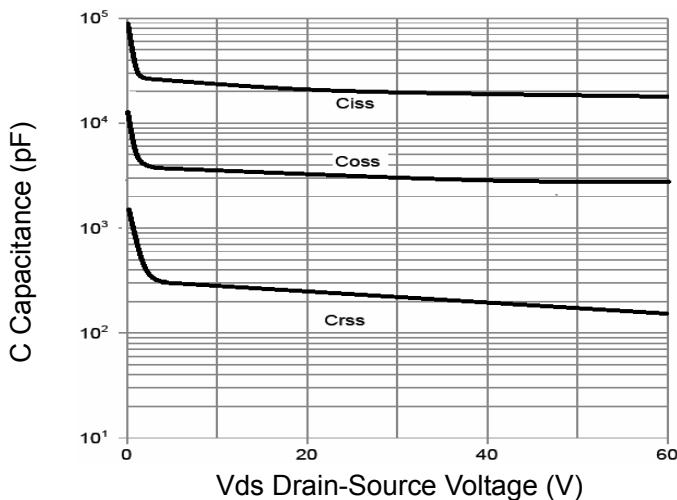


Figure 7 Capacitance vs Vds

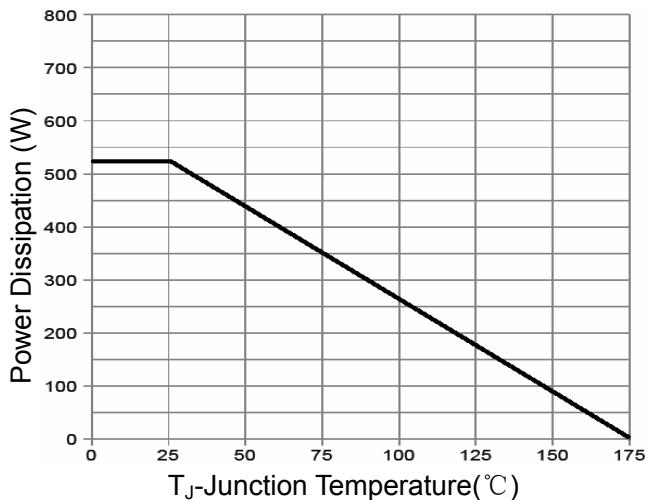


Figure 9 Power De-rating

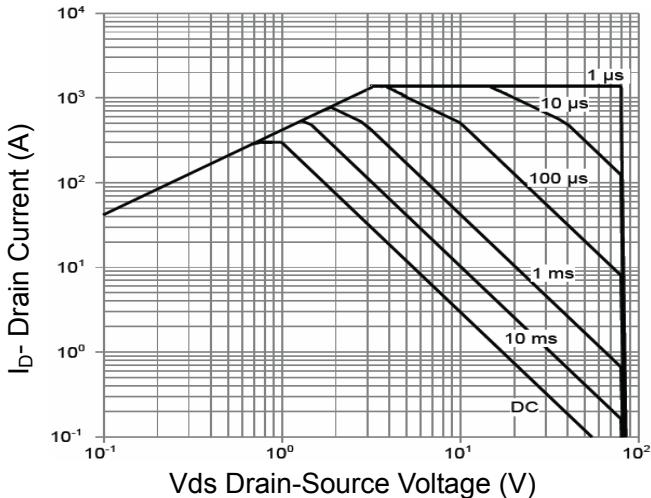


Figure 8 Safe Operation Area

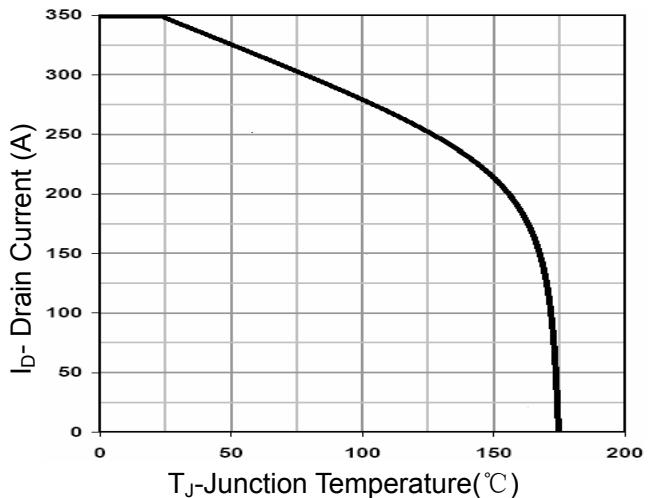


Figure 10 Current De-rating

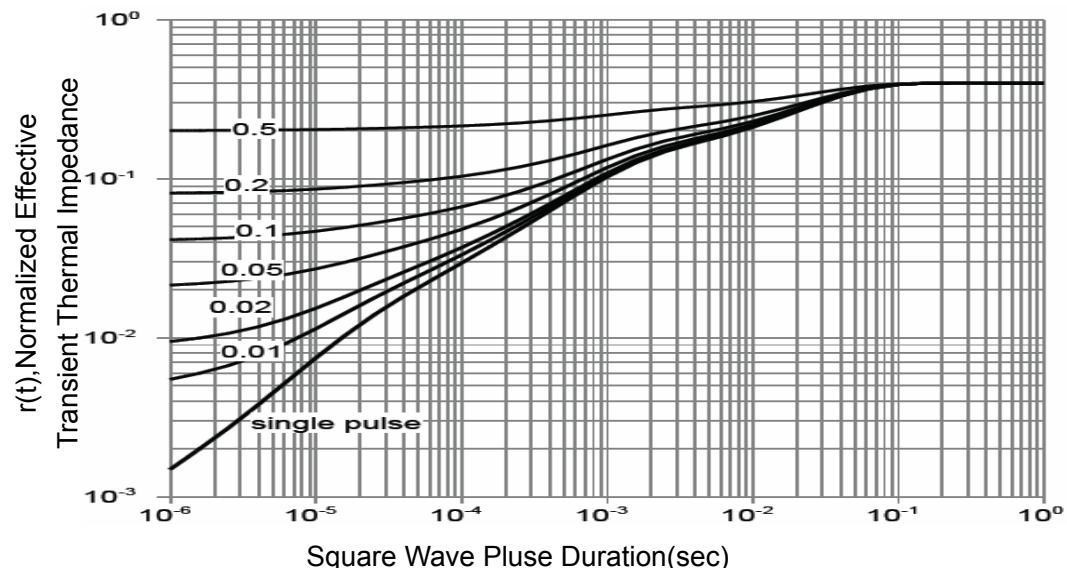
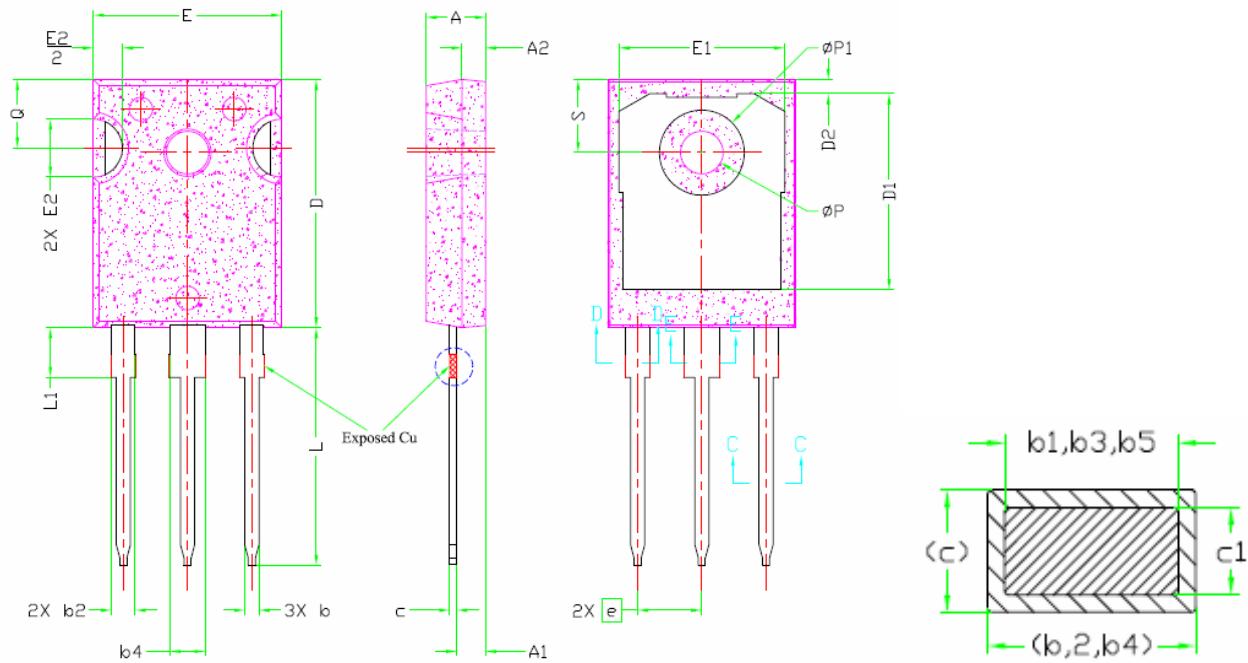


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-247 Package Information



Symbol	Dimensions In Millimeters		
	Min.	Nom.	Max.
A	4.83	5.02	5.21
A1	2.29	2.41	2.55
A2	1.50	2.00	2.49
b	1.12	1.20	1.33
b1	1.12	1.20	1.28
b2	1.91	2.00	2.39
b3	1.91	2.00	2.34
b4	2.87	3.00	3.22
b5	2.87	3.00	3.18
c	0.55	0.60	0.69
c1	0.55	0.60	0.65
D	20.80	20.95	21.1
D1	16.25	16.55	17.65
D2	0.51	1.19	1.35
E	15.75	15.94	16.13
E1	13.46	14.02	14.16
E2	4.32	4.91	5.49
L	19.81	20.07	20.32
L1	4.10	4.19	4.40
Q	5.39	5.79	6.20
ØP	3.56	3.61	3.65
S	6.04	6.17	6.30

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